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L Number	Hits		DB	Time stamp
_	6039	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/30 15:08
-	0	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire	USPAT; US-PGPUB; EPO; JPO;	2003/01/30 15:10
_	184	adj bomds) (integrated adj circuit) and (contact or	DERWENT USPAT;	-2003/01/30
	104	output/input adj pads) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds)	US-PGPUB; EPO; JPO; DERWENT	15:15
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 10:15
-	118		USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 10:25
-	0	"09888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/19 15:37
-	0	"09888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/06/20 10:14
-	0	"09/888674" and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 11:45
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or layer) and (passivation adj region or layer)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 09:59
-	0		USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:24
-	0		USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:25
-	4	(integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire adj bonds) and (barrier)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 12:26
-	28	1	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/02/01 15:10
-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/01/31 15:38
-	23	layer) and (passivation adj region or layer) (integrated adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier) and (lead)	USPAT; US-PGPUB; EPO; JPO; DERWENT	2003/07/07 10:03

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- 0 "20010011764" and gold USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;					13:21
- 0 "20010011764" and gold USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;		1			
US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/19 US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;					1 2002 (05/22
EPO; JPO; DERWENT USPAT; 2003/06/19 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPGPUB; EPO; JPO;	-	0	"20010011764" and gold		1 1
- 2 "20010011764"					13:52
- 2 "20010011764" USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;)
US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;					1 2002 (25 (25
- 0 "6441487" and (gold)	-	2	"20010011764"		
- 0 "6441487" and (gold) USPAT; 2003/06/19 US-PGPUB; EPO; JPO; DERWENT USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	1			· ·	13:52
- 0 "6441487" and (gold) USPAT; 2003/06/19 15:37 - 9 "5234149" and (gold) USPAT; 2003/06/19 15:37 USPAT; 2003/06/19 USPAT; 2003/06/19 USPAT; US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO; USPAT; US-PGPUB; US	1	1			
US-PGPUB; EPO; JPO; DERWENT USPAT; US-PGPUB; US-PGPUB; US-PGPUB; DERWENT USPAT; US-PGPUB; EPO; JPO; US-PGPUB; EPO; JPO;	1			l .	1 2002 (05 (20
EPO; JPO; DERWENT USPAT; 2003/06/19 US-PGPUB; EPO; JPO;	-	0	"6441487" and (gold)		
DERWENT USPAT; US-PGPUB; EPO; JPO;					15:37
- 9 "5234149" and (gold) USPAT; 2003/06/19 US-PGPUB; 15:38 EPO; JPO;	1				
US-PGPUB; 15:38 EPO; JPO;	1	_			1 0000 100 150
EPO; JPO;	l -	9	"5234149" and (gold)		1
					12:38
DERWENT					
		L	<u> </u>	DERWENT	<u> </u>

-	6	"5234149" and (under adj bump)	USPAT; US-PGPUB;	2003/06/19 19:18
			EPO; JPO;	
			DERWENT	
-	0	5234149.pn. and (under adj bump)	USPAT;	2003/06/19
			US-PGPUB;	17:48
			EPO; JPO;	
	1	"20010011764" and (under adj bump)	DERWENT USPAT;	2003/06/19
-	*	20010011764 and (under ad) bump)	US-PGPUB;	19:18
			EPO; JPO;	13.10
			DERWENT	
-	1	"20010011764" and (electroplating)	USPAT;	2003/06/19
			US-PGPUB;	19:19
			EPO; JPO;	
	10	HE224140H and (maklasses)	DERWENT USPAT;	2003/06/20
-	10	"5234149" and (reflow\$3)	US-PGPUB;	10:15
			EPO; JPO;	10.13
			DERWENT	
-	0	5234149.pn. and (reflow\$3)	USPAT;	2003/06/20
			US-PGPUB;	10:16
			EPO; JPO;	
		20010011764 mm 1 / 51 421	DERWENT	2002/06/20
-	1	20010011764.pn. and (reflow\$3)	USPAT; US-PGPUB;	2003/06/20
			EPO; JPO;	10.31
	1		DERWENT	
_	1	20010011764.pn. and (lead)	USPAT;	2003/06/20
		• • • •	US-PGPUB;	10:34
			EPO; JPO;	
			DERWENT	2003/06/20
-	1	20010011764.pn. and (reflow\$3)	USPAT; US-PGPUB;	2003/06/20 11:05
		+	EPO; JPO;	11.03
			DERWENT	
_	0	20010011764.pn. and (selective adj	USPAT;	2003/06/20
		electroplating)	US-PGPUB;	11:05
			EPO; JPO;	
			DERWENT	2002/07/07
-	126	(integrated adj circuit) and (contact adj	USPAT;	2003/07/07
:		pad) and (under adj bump adj region or layer) and (solder adj bonds) and (wire	US-PGPUB; EPO; JPO;	10.01
İ		adj bonds) and (barrier adj region or	DERWENT	
1		layer) and (passivation adj region or		
		layer)		
-	0	438/14,15,762,763.ccls. and (integrated	USPAT;	2003/10/29
		adj circuit) and (contact adj pad) and	US-PGPUB;	11:25
		((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	EPO; JPO; DERWENT	
_	32	and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj	USPAT;	2003/07/07
	32	pad) and ((under adj bump adj metallurgy)	US-PGPUB;	10:03
		or ubm) and (solder) and (wire) and	EPO; JPO;	
		(barrier) and (lead)	DERWENT	
-	1103	((bond adj pad) or terminal) near (copper	USPAT;	2003/10/28
	1	or Cu)	US-PGPUB;	16:44
			EPO; JPO; DERWENT	
_	545	((bond adj pad) or terminal) near (copper	USPAT;	2003/10/28
	373	or Cu) and ((wire adj bonding) or wire)	US-PGPUB;	16:46
		,, ,,,,	EPO; JPO;	
ļ			DERWENT	
-	1	6133065.pn. and wire and solder	USPAT;	2003/10/29
			US-PGPUB;	11:59
l			EPO; JPO; DERWENT	
1_	0	6133065.pn. and wire and solder and	USPAT;	2003/10/29
		underbump	US-PGPUB;	11:59
	1	<u></u>	EPO; JPO;	
			DERWENT	

47	

-	0	6133065.pn. and underbump	USPAT;	2003/10/29
			US-PGPUB;	12:09
Ì			EPO; JPO;	
			DERWENT	
_	1 1	6335104.pn. and wire and solder	USPAT;	2003/10/29
	-	door to the transfer of the tr	US-PGPUB;	12:29
ļ			EPO; JPO;	12.23
			h .	ļ
			DERWENT	
-	2	4268849.pn.	USPAT;	2003/10/29
1			US-PGPUB;	12:33
			EPO; JPO;	
1			DERWENT	i
_	l n	4268849.pn. and wire and solder	USPAT;	2003/10/29
	ľ	4200045.pii. and wife and Sorder	US-PGPUB;	12:34
1				12.54
			EPO; JPO;	
			DERWENT	
-	1	6335104.pn. and solder	USPAT;	2003/11/07
			US-PGPUB;	12:07
1			EPO; JPO;	
			DERWENT	
_	1	20010011764.pn. and wire	USPAT;	2003/11/07
	1	20020022,01.piii aiia #210	US-PGPUB;	12:37
				12.37
			EPO; JPO;	1
	i		DERWENT	1
-	1	20010020745.pn. and wire	USPAT;	2003/11/07
			US-PGPUB;	12:38
i		·	EPO; JPO;	
		`	DERWENT	1
_	1	20010020745.pn. and solder	USPAT;	2003/11/07
		1 1010020, 10. pii. ana botact	US-PGPUB;	12:38
1				12.30
			EPO; JPO;	
		1	DERWENT	
-	2	20020143830.pn.	USPAT;	2003/11/12
			US-PGPUB;	11:55
			EPO; JPO;	1
1			DERWENT	1
1_	2	20030143830.pn.	USPAT;	2003/11/12
			US-PGPUB;	11:55
	1			11.33
1			EPO; JPO;	
			DERWENT	1
-	0	20030143830.pn. and solder	USPAT;	2003/11/12
1 .			US-PGPUB;	11:57
•			EPO; JPO;	1
	Ì		DERWENT	
l _	2	20010011764.pn.	USPAT;	2003/11/12
	۱	20010011/04.pm.	US-PGPUB;	
				11:58
			EPO; JPO;	
			DERWENT	
-	2	20010011764.pn.	USPAT;	2003/11/12
1			US-PGPUB;	11:58
			EPO; JPO;	[
]			DERWENT	j
1 _	1	20010011764.pn. and wire	USPAT;	2003/11/12
		Lootoott/oj.pii. and wite	US-PGPUB;	12:19
			· ·	12.19
			EPO; JPO;	1
			DERWENT	
-	1	20010011764.pn. and (reflow same solder)	USPAT;	2003/11/12
			US-PGPUB;	13:44
			EPO; JPO;	
			DERWENT	
_	1	20010011764.pn. and (reflow same solder	USPAT;	2003/11/12
1		same diffusion)	US-PGPUB;	13:47
		June dillusion,		13.37
			EPO; JPO;	
			DERWENT	
~	1	20010011764.pn. and (reflow same solder	USPAT;	2003/11/12
		same (diffusion or diffus\$3))	US-PGPUB;	13:48
			EPO; JPO;	
			DERWENT	
				·-,